



HBF4522D

NPN TRIPLE DIFFUSION PLANAR TRANSISTOR

Description

HBF4522D is designed for use in the monitor dynamic focus circuit. It can be used up to 19" monitor with working frequency as high as 100KHz.

Features

- High Breakdown Voltage
- Low C-E Saturation Voltage
- High Cutoff Frequency
- High Current Gain

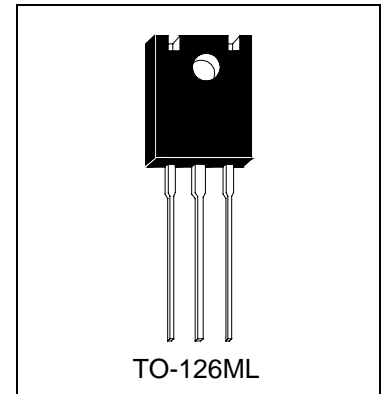
Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
 Storage Temperature -50 ~ +150 °C
 Junction Temperature +150 °C
- Maximum Power Dissipation
 Total Power Dissipation (Ta=25°C)..... 1.5 W
 Total Power Dissipation (Tc=25°C) 20 W
- Maximum Voltages and Currents
 BVCBO Collector to Base Voltage..... 550 V
 BVCEO Collector to Emitter Voltage..... 550 V
 BVEBO Emitter to Base Voltage..... 5 V
 IC Collector Current..... 100 mA
 IB Base Current..... 20 mA

Electrical Characteristics (Ta=25°C)

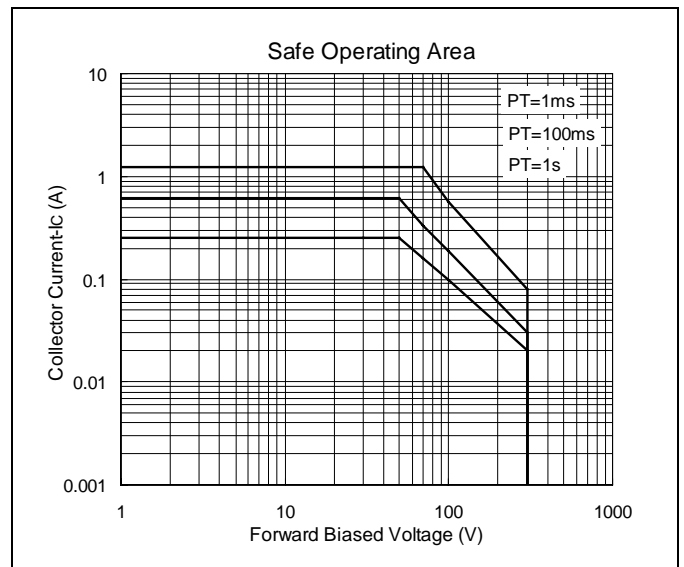
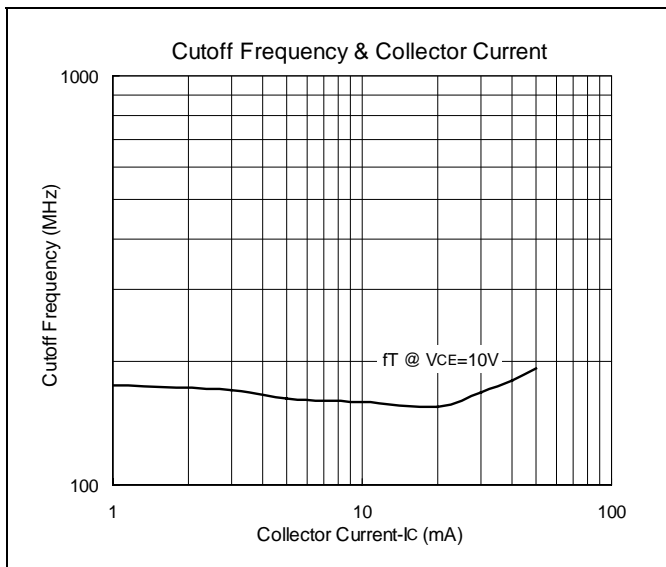
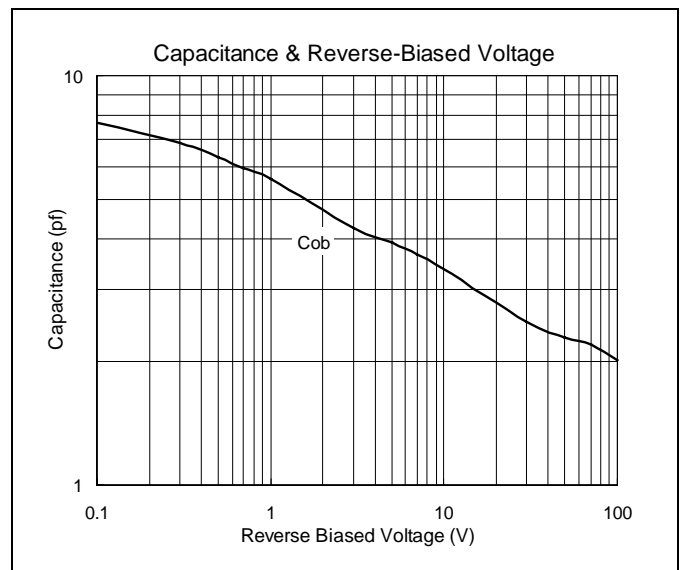
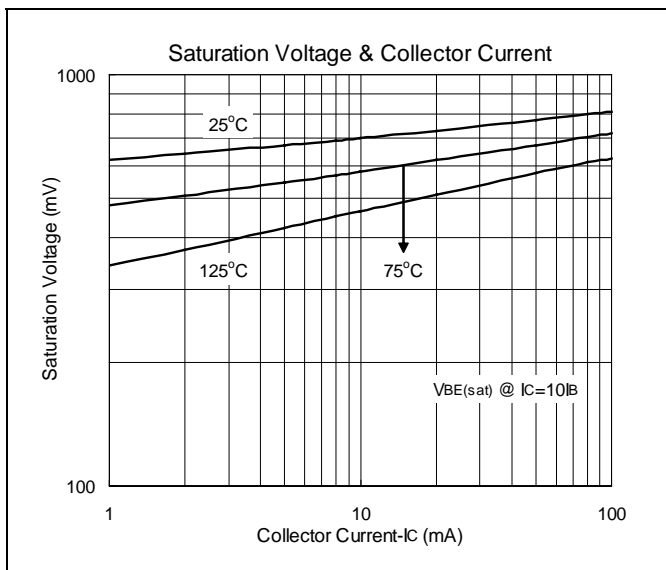
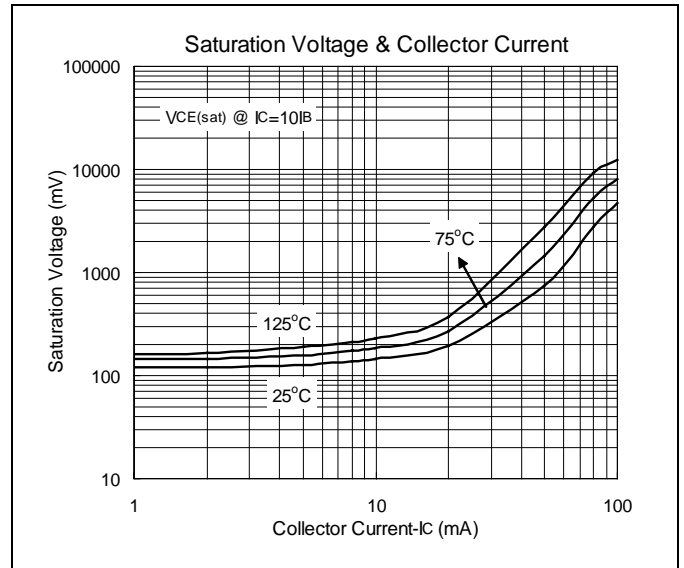
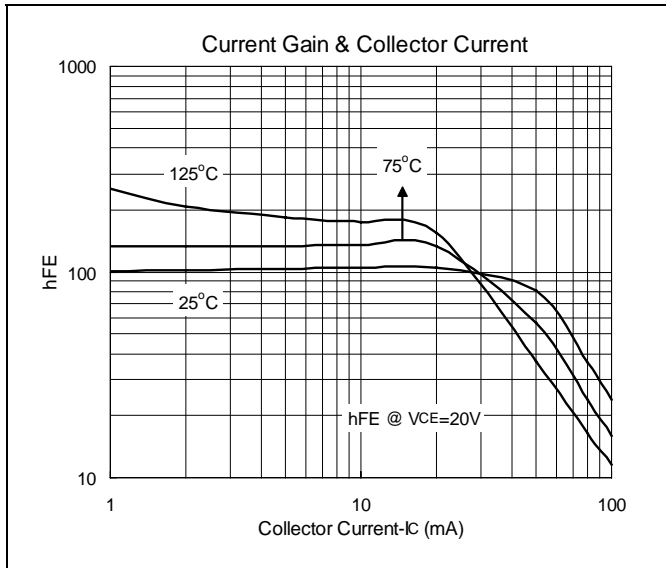
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCEO	550	-	-	V	IC=1mA
BVCBO	550	-	-	V	IC=100uA
BVEBO	7	-	-	V	IE=10uA,
ICBO	-	-	1	uA	VCB=500V
IEBO	-	-	100	nA	VEB=5V
*VCE(sat)	-	0.35	0.5	V	IC=30mA, IB=3mA
*hFE	100	150	200		VCE=20V, IC=30mA
fT	90	-	-	MHz	VCE=10V, IE=30mA, ftest=100MHz

*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%



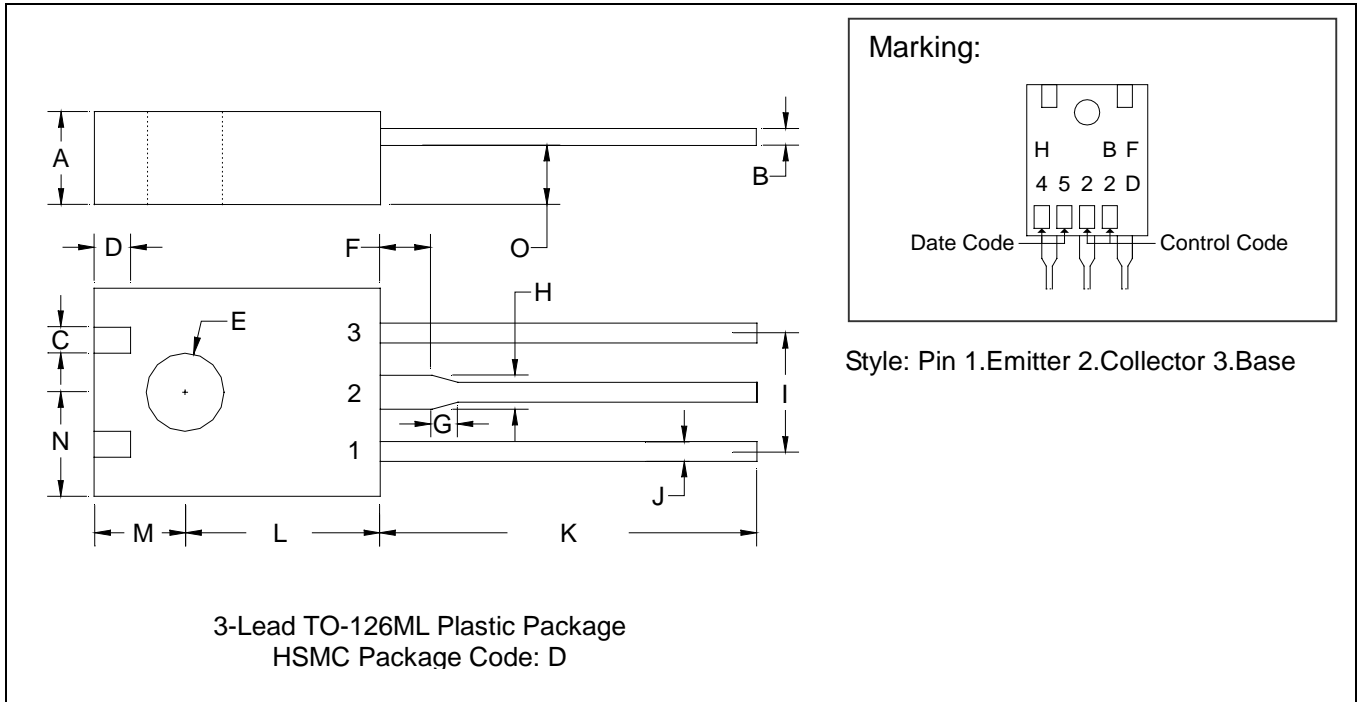


Characteristics Curve





TO-126ML Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1356	0.1457	3.44	3.70	I	-	*0.1795	-	*4.56
B	0.0170	0.0272	0.43	0.69	J	0.0268	0.0331	0.68	0.84
C	0.0344	0.0444	0.87	1.12	K	0.5512	0.5906	14.00	15.00
D	0.0501	0.0601	1.27	1.52	L	0.2903	0.3003	7.37	7.62
E	0.1131	0.1231	2.87	3.12	M	0.1378	0.1478	3.50	3.75
F	0.0737	0.0837	1.87	2.12	N	0.1525	0.1625	3.87	4.12
G	0.0294	0.0494	0.74	1.25	O	0.0740	0.0842	1.88	2.14
H	0.0462	0.0562	1.17	1.42					

Notes: 1.Dimension and tolerance based on our Spec. dated Mar. 6,1995.
 2.Controlling dimension: millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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